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Part Number: [5022503391](#)
Status: **Active**
Description: 0.30mm (.012") Pitch Easy-On™ BackFlip™ FPC Connector, Right Angle, SMT,Dual Contact Style, 0.90mm (.012") Mated Height, 33 Circuits

Documents:
[3D Model](#) [Product Specification PS-502250-001 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

General

Product Family FFC/FPC Connectors
Series [502250](#)
Product Name BackFlip™, Easy-On™

Physical

Circuits (Loaded) 33
Color - Resin Black, Natural
Contact Position Dual
Durability (mating cycles max) 10
Entry Angle 90° Angle
Mated Height (in) 0.035 In
Mated Height (mm) 0.90 mm
Material - Metal Copper-Nickel-Tin
Material - Plating Mating Gold
Material - Plating Termination Gold
Number of Rows 1
Orientation Right Angle
PCB Locator No
PCB Retention Yes
Packaging Type Embossed Tape on Reel
Pitch - Mating Interface (in) 0.012 In
Pitch - Mating Interface (mm) 0.30 mm
Polarized to PCB Yes
Stackable No
Temperature Range - Operating -25°C to +85°C
Termination Interface: Style Surface Mount
Wire/Cable Type FPC only

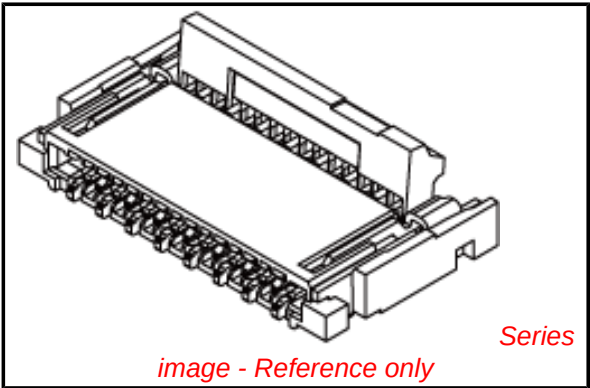
Electrical

Current - Maximum per Contact 0.2A
Voltage - Maximum 50V AC (RMS)/DC

Material Info

Reference - Drawing Numbers

Product Specification PS-502250-001, RPS-502250-002, RPS-502250-003,
RPS-502250-005, RPS-502250-007
Sales Drawing SD-502250-003, SD-502250-004



EU RoHS

**ELV and RoHS
Compliant**
REACH SVHC
Not Reviewed
**Halogen-Free
Status**

China RoHS

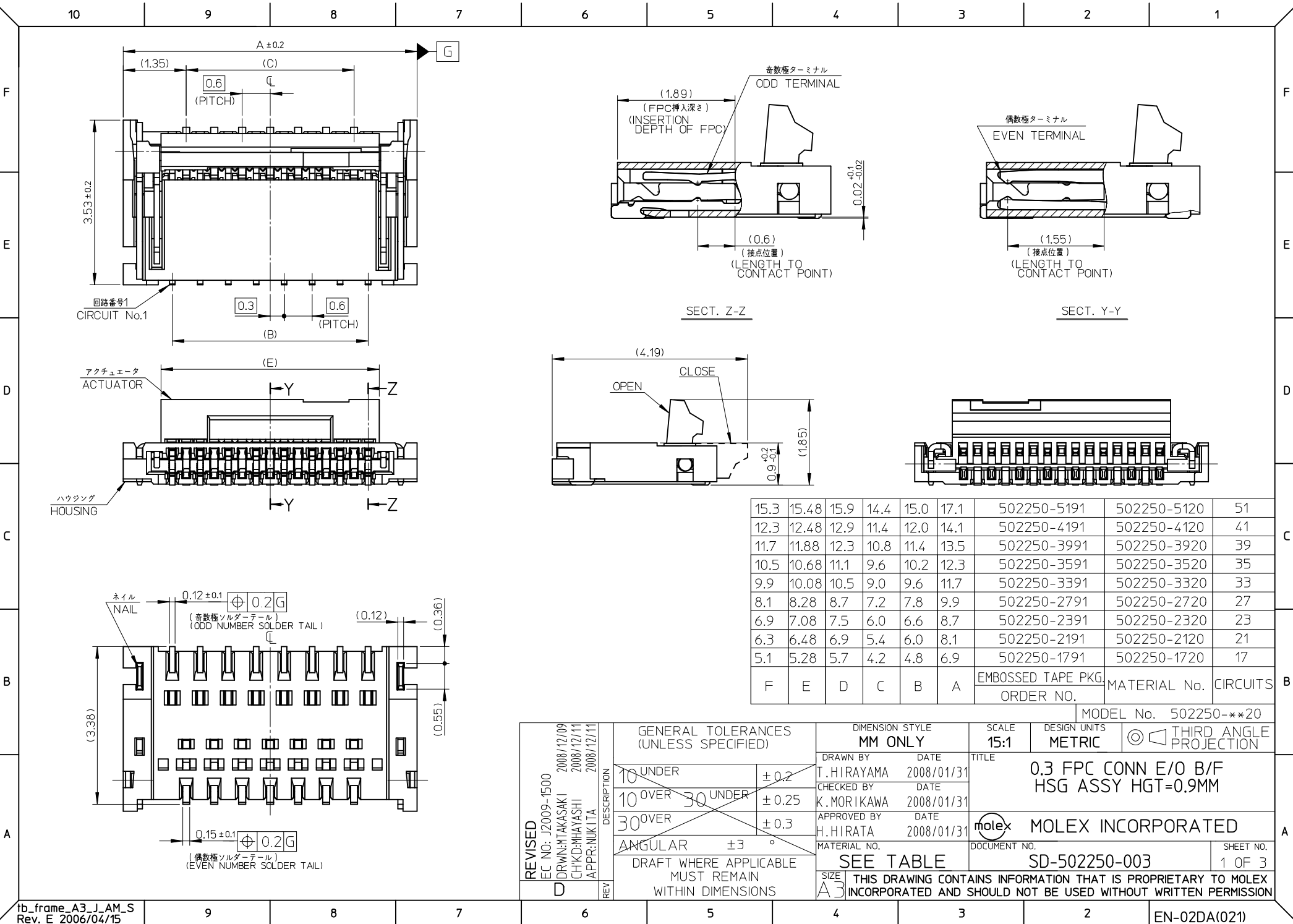


**Need more information on product
environmental compliance?**

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of
Compliance, [click here](#)

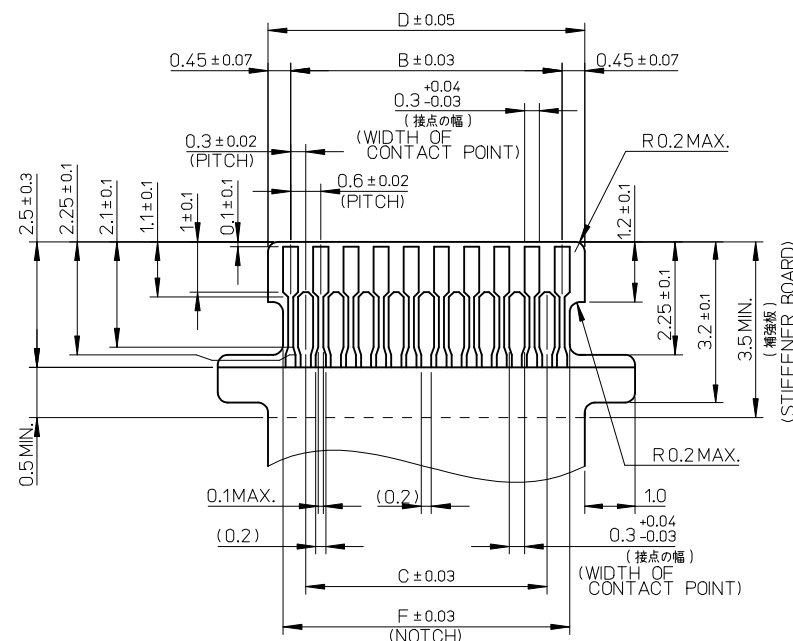
Please visit the [Contact Us](#) section for any
non-product compliance questions.

Search Parts in this Series
[502250Series](#)



15.3	15.48	15.9	14.4	15.0	17.1	502250-5191	502250-5120	51
12.3	12.48	12.9	11.4	12.0	14.1	502250-4191	502250-4120	41
11.7	11.88	12.3	10.8	11.4	13.5	502250-3991	502250-3920	39
10.5	10.68	11.1	9.6	10.2	12.3	502250-3591	502250-3520	35
9.9	10.08	10.5	9.0	9.6	11.7	502250-3391	502250-3320	33
8.1	8.28	8.7	7.2	7.8	9.9	502250-2791	502250-2720	27
6.9	7.08	7.5	6.0	6.6	8.7	502250-2391	502250-2320	23
6.3	6.48	6.9	5.4	6.0	8.1	502250-2191	502250-2120	21
5.1	5.28	5.7	4.2	4.8	6.9	502250-1791	502250-1720	17
F	E	D	C	B	A	EMBOSSED TAPE PKG ORDER NO.	MATERIAL No.	CIRCUITS

REVISED EC NO: J2009-1500 D DRAWN: TAKASAKI CHKD: HAYASHI APPR: NUKITA	DESCRIPTION 2008/12/09 2008/12/11 2008/12/11	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 15:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER ±0.2		DRAWN BY DATE T. HIRAYAMA 2008/01/31		TITLE 0.3 FPC CONN E/O B/F HSG ASSY HGT=0.9MM			
		10 OVER 30 UNDER ±0.25		CHECKED BY DATE K. MORIKAWA 2008/01/31					
		30 OVER ±0.3		APPROVED BY DATE H. HIRATA 2008/01/31		MOLEX INCORPORATED			
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-502250-003		1 OF 3	
				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



挿入位置確認用耳つきFPC
WITH EARS FOR FPC INSERTION ALIGNMENT

(仕上がり厚さ: 0.2 ± 0.03)
(THICKNESS : 0.2 ± 0.03)

抜き方向は、導体側から補強板側を推奨致します。
 補強フィルム材質は、ポリイミドを推奨致します。
 接着剤は熱硬化接着剤を推奨致します。
 尚、接着剤の接点部への付着は導通不良の原因になりますので、
 染み出しが無い様、お願い致します。

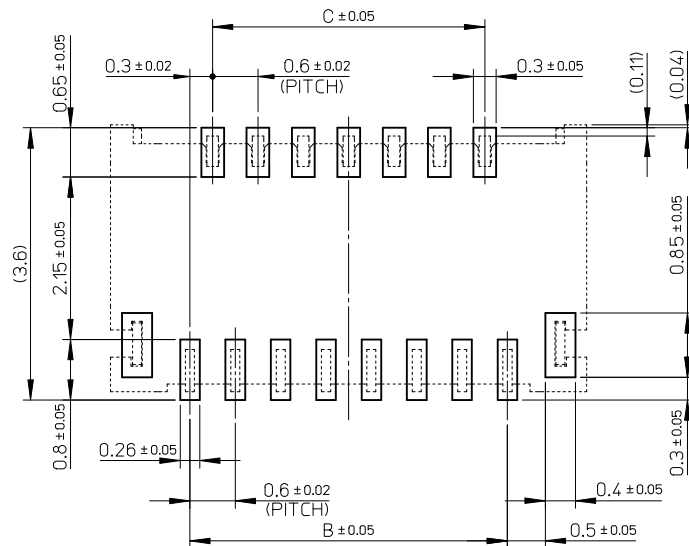
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFNER FILM SIDE.

STIFFENER FILM : POLYIMIDE

BONDING AGENT : THERMOSETTING AGENT

PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND
BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE
CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

tb_frame_A3_J_AM_S
Rev. E 2006/04/15



推奨基板レイアウト図 (マウント面)
P.CBOARD PATTERN
RECOMMENDED DIMENSION
(MOUNTING AREA)

注記 NOTES

1. 使用材料 MATERIAL
ハウジング : 液晶ポリマー ガラス充填 UL94V-0 (ナチュラル)
HOUSING : LIQUID CRYSTAL POLYMER (GLASS FILLED)
UL94V-0(COLOR:NATURAL)
アクチュエータ : ポリフェニレンサルファイド ガラス充填 UL94V-0 (黒)
ACTUATOR : POLYPHENYLENE SULFIDE (GLASS FILLED)
UL94V-0(COLOR:BLACK)
ターミナル : 銅ニッケルスズ合金、ニッケル下地部分金メッキ (接触部及びテール部)
TERMINAL : COPPER NICKEL TIN ALLOY,
PARTLY GOLD(CONTACT,TAIL) OVER NICKEL PLATING
ネイル : リン青銅、ニッケル下地 錫めっき
FITTING NAIL : PHOSPHOR-BRONZE, TIN OVER NICKEL PLATING
2. ソルダータール半田付け面、及びネイル半田付け面の平坦度 : 0.1mmMAX.
COPLANARITY OF SOLDER TAILS AND FITTING NAILS
TO BE 0.1mm MAX.
3. 基板実装前にアクチュエータを操作しないで下さい。
PLEASE DO NOT OPERATE THE ACTUATOR BEFORE MOUNTING.
必ず基板に実装し、FPCを挿入してからアクチュエータを操作して下さい。
PLEASE OPERATE THE ACTUATOR AFTER MOUNTING ON
THE SUBSTRATE,AND MATING FPC.
4. 推奨メタルマスク RECOMMENDED METAL MASK SPECIFICATION
マスク厚 : 0.1mm MASK THICKNESS : 0.1mm
なお、貴社にて上記以外でご利用頂く場合は、事前に確認頂きますようお願い致します。
WHEN USE IT OTHER THAN THE ABOVE IN YOUR COMPANY,
PLEASE CONFIRM IT BEFOREHAND.
5. ELV 及び RoHS適合品
ELV AND RoHS COMPLIANT.

SEE SHEET 1 EC NO.: J2009-1500 DRWN:MTAKASAKI 2008/12/09 CHKD:MHAYASHI 2008/12/11 APPR:NUKITA 2008/12/11	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
		10 UNDER	±0.2	T. HIRAYAMA	2008/01/31	TITLE 0.3 FPC CONN E/O B/F HSG ASSY HGT=0.9MM		
		10 OVER 30 UNDER	±0.25	CHECKED BY	DATE			
		30 OVER	±0.3	K. MORIKAWA	2008/01/31			
				APPROVED BY	DATE	 MOLEX INCORPORATED		
	ANGULAR	±3 °	H. HIRATA	2008/01/31				
					MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
D	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1		SD-502250-003		3 OF 3
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

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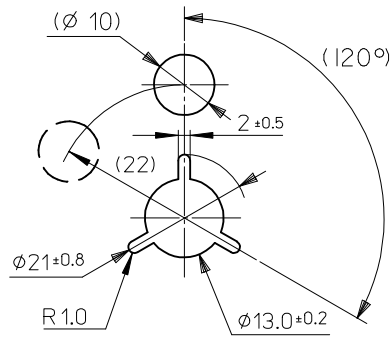
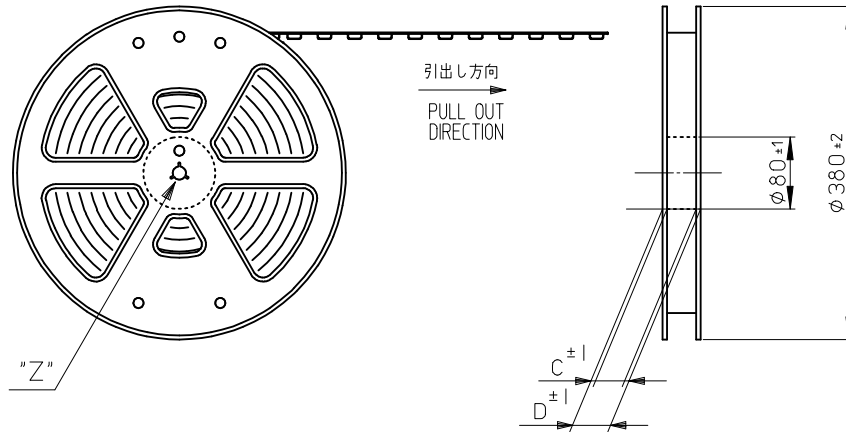
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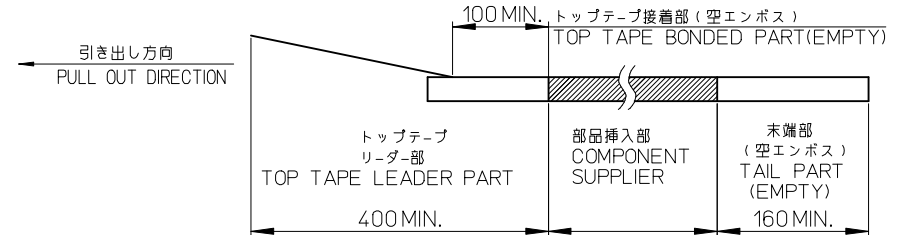
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DETAIL "Z"

NOTES

- 製品 (502250-**20) の詳細寸法については、
図面SD-502250-003をご参照ください。
IN THE PACKAGE, PART NO. 502250-**20 DETAILED DIMENSIONS,
REFER TO SALES DRAWING NO. SD-502250-003.
- 梱包数量: 3000 個/リール
NUMBER OF CONNECTORS: 3000 PCS/REEL
- リードテープ長さ
LEAD TAPE LENGTH



- 材料 (MATERIAL)
キャリアテープ (CARRIER TAPE): ポリスチレン (POLYSTYRENE)
トップテープ (TOP TAPE): PET, OTHER
リール (REEL): ポリスチレン (POLYSTYRENE) <リサイクル材を含む>
<RECYCLE MATERIAL CONTAINED>
- ELV 及び RoHS 適合品
ELV AND RoHS COMPLIANT.

REVISED	EC NO.: J2009-1500	DRWN: MTAKASAKI CHKD: MHAYASHI APPR: NUKITA	2008/12/09 2008/12/11 2008/12/11	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
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					10 OVER 30 UNDER ±0.25		CHECKED BY DATE K. MORIKAWA 2008/01/31					
					30 OVER ±0.3		APPROVED BY DATE H. HIRATA 2008/01/31		MOLEX MOLEX INCORPORATED			
					ANGULAR ±3 °		MATERIAL NO.					
					DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-502250-004		1 OF 3	

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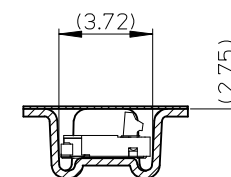
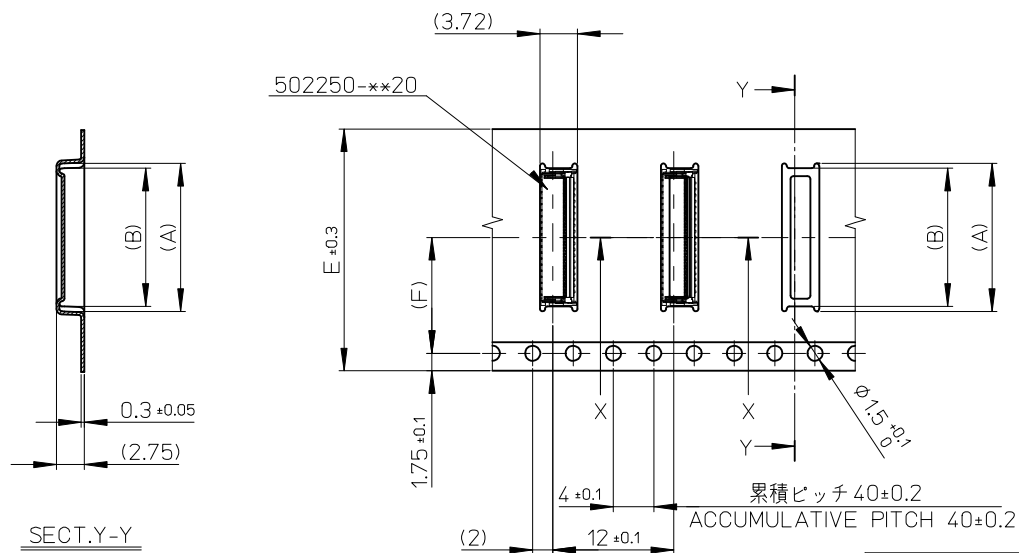
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引き出し方向
PULL OUT DIRECTION



24	11.5	24	29.4	25.4	14.3	15.3	502250-4191	41	
					13.7	14.7	502250-3991	39	
					12.5	13.5	502250-3591	35	
					11.9	12.9	502250-3391	33	
					10.1	11.1	502250-2791	27	
					8.9	9.9	502250-2391	23	
					8.3	9.3	502250-2191	21	
16	7.5	16	21.4	17.4	7.1	8.1	502250-1791	17	
キャリアテープ幅 CARRIER TAPE WIDTH		(F)	E	D	C	(B)	(A)	製品番号 MATERIAL NO.	極数 CIRCUIT

SEE SHEET 1 EC NO.: J2009-1500 DRWN: MTAKASAKI CHKD: HAYASHI APPR: NUKITA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
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		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		
	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-502250-004		2 OF 3
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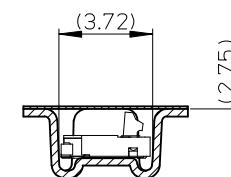
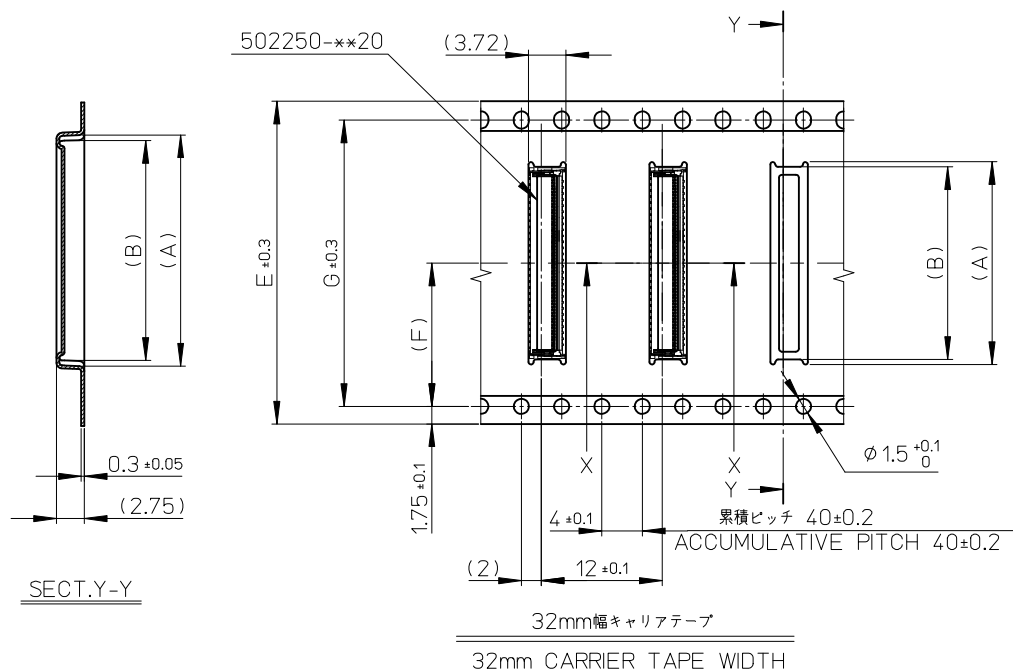
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引き出し方向
PULL OUT DIRECTION



SECT.X-X

32	28.4	14.2	32	37.4	33.4	17.3	18.3	502250-5191	51
キャリアテープ幅 CARRIER TAPE WIDTH	G	(F)	E	D	C	(B)	(A)	製品番号 MATERIAL NO.	極数 CIRCUIT

SEE SHEET 1 EC NO.: J2009-1500 DRWN: MTAKASAKI 2008/12/09 CHKD: HAYASHI 2008/12/11 APPR: NUKITA 2008/12/11	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
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	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-502250-004		3 OF 3		
	REV			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

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